L Number	Hits	Search Text	DB	Time stamp
12	238	interposer and dicing and (chip or substrate or wafer)	USPAT; US-PGPUB	2003/06/20 17:09
13	120	(interposer and dicing and (chip or substrate or wafer)) and @ad<=20001002	USPAT; US-PGPUB	2003/06/20 17:18
14	89	((interposer and dicing and (chip or substrate or wafer)) and @ad<=20001002) and test$3	USPAT; US-PGPUB	2003/06/20 16:25
15	14	interposer and dicing and (chip or substrate or wafer)	EPO; JPO; DERWENT; IBM_TDB	2003/06/20 17:09
16	5	jerry near2 kline	USPAT; US-PGPUB	2003/06/20 17:16

	U	1	Document ID	Issue Dat	Pages	Titl	Curr nt OR
1	☐	☐	US 20020097063 A1	20020725	9	Wafer level interposer	324/765
2	☐	☐	US 6537831 B1	20030325	18	Method for selecting components for a matched set using a multi wafer interposer	438/14
3	☐	☐	US 6483330 B1	20021119	18	Method for selecting components for a matched set using wafer interposers	324/754
4	☐	☐	US 6483043 B1	20021119	12	Chip assembly with integrated power distribution between a wafer interposer and an integrated circuit chip	174/262
5	☐	☐	US 6392428 B1	20020521	8	Wafer level interposer	324/755

	Current XRef	Retrieval Classif	Inventor	S	C	P	2	3	4	5
1			Kline, Jerry D.	☒	☐	☐	☐	☐	☐	☐
2	438/106; 438/107		Kline, Jerry D.	☒	☐	☐	☐	☐	☐	☐
3	324/158.1; 324/757; 324/765; 438/17; 438/18		Kline, Jerry D.	☒	☐	☐	☐	☐	☐	☐
4	174/260; 361/601; 361/794		Kline, Jerry D.	☒	☐	☐	☐	☐	☐	☐
5	257/E21.525; 257/E23.067; 324/158.1; 324/754		Kline, Jerry D. et al.	☒	☐	☐	☐	☐	☐	☐

	U	1 [1]	Docum nt ID	Issue Dat	Pages	Title	Current OR
1	☐	☒	US 20020011663 A1	20020131	39	FACE-UP SEMICONDUCTOR CHIP ASSEMBLIES	257/734
2	☐	☒	US 6498387 B1	20021224	11	Wafer level package and the process of the same	257/620
3	☐	☒	US 6489678 B1	20021203	9	High performance multi-chip flip chip package	257/723
4	☐	☒	US 6432744 B1	20020813	16	Wafer-scale assembly of chip-size packages	438/108
5	☐	☒	US 6392306 B1	20020521	41	Semiconductor chip assembly with anisotropic conductive adhesive connections	257/783
6	☐	☒	US 6372527 B1	20020416	43	Methods of making semiconductor chip assemblies	438/15

	Current XRef	Retrieval Classif	Inventor	S	C	P	2	3	4	5
1			Khandros, Igor Y. et al.	☒	☐	☐	☐	☐	☐	☐
2	257/612; 257/678; 257/753		Yang, Wen-Ken	☒	☐	☐	☐	☐	☐	☐
3	257/666; 257/693; 257/737; 257/E23.026		Joshi, Rajeev	☒	☐	☐	☐	☐	☐	☐
4	438/118; 438/612; 438/616		Amador, Gonzalo et al.	☒	☐	☐	☐	☐	☐	☐
5	257/784		Khandros, Igor Y. et al.	☒	☐	☐	☐	☐	☐	☐
6	257/E21.511; 257/E21.606; 257/E21.705; 257/E23.019; 257/E23.061; 257/E23.065; 257/E23.066; 257/E23.067; 257/E23.124; 257/E23.13; 257/E25.029; 438/113; 438/125		Khandros, Igor Y. et al.	☒	☐	☐	☐	☐	☐	☐

	U	1 [1]	Document ID	Issue Date	Pages	Titl	Current OR
7	☐	☒	US 6281046 B1	20010828	9	Method of forming an integrated circuit package at a wafer level	438/113
8	☐	☒	US 6032356 A	20000307	39	Wafer-level test and burn-in, and semiconductor process	29/843

	Current XRef	Retrieval Classif	Inventor	S	C	P	2	3	4	5
7	257/738; 257/778; 257/E21.503; 257/E21.508; 257/E23.065; 257/E23.124; 438/108; 438/615; 438/616		Lam, Ken M.	☒	☐	☐	☐	☐	☐	☐
8	257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 29/842; 29/874; 324/756; 439/56; 439/591; 439/66		Eldridge, Benjamin N. et al.	☒	☐	☐	☐	☐	☐	☐

	U	1 [1]	Document ID	Issue Date	Pages	Title	Current OR
9	☐	☒	US 5998228 A	19991207	39	Method of testing semiconductor	438/15

	Current XR f	Retrieval Classif	Inventor	S	C	P	2	3	4	5
9	228/179.1; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 324/754; 324/762; 428/601; 428/620		Eldridge, Benjamin N. et al.	☒	☐	☐	☐	☐	☐	☐

	U	1 [1]	Document ID	Issue Date	Pages	Title	Current OR
10	☐	☒	US 5832601 A	19981110	39	Method of making temporary connections between electronic components	29/843

	Current XRef	R trieval Classif	Inventor	S	C	P	2	3	4	5
10	257/620; 257/665; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 29/840; 438/14; 438/18		Eldridge, Benjamin N. et al.	☒	☐	☐	☐	☐	☐	☐